


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/23/14173	
<b>1.3 Title of PCN</b>	ST Calamba (Philippines) UFQFPN 7x7 48L package line additional source for STM32G07x/08x, STM32G41x/G47x/48x and STM32C031x listed products	
<b>1.4 Product Category</b>	STM32C0x, STM32G0x, STM32G4x.	
<b>1.5 Issue date</b>	2023-10-25	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	NEMETH KRISZTINA
<b>2.1.2 Phone</b>	+49 89460062210
<b>2.1.3 Email</b>	krisztina.nemeth@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Calamba (Philippines)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Back-End Sources - ASE KaoHsiung (Taiwan) - STATSChipPAC JSCC (China)	Back-End Sources - ASE KaoHsiung (Taiwan) / Bonding Wire is Gold - STATSChipPAC JSCC (China) / Bonding Wire is Gold - ST Calamba (Philippines) / Bonding Wire is Copper Alloy
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	Lead color and surface finish change depending on leadfinishing. Package darkness changes depending on molding compound. Pin1 identifier might change in terms of form and positioning. Marking position and size could be different upon assembly site, without any loss of information.	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to the success on the market of STM32 devices, ST General Purpose Microcontrollers Group decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Change is visible through assembly traceability plant, in the marking: - "GQ" for Stats ChipPAC Jiangyin China (JSCC) - "AA" for ASE Kaohsiung Taiwan - "78" for ST Calamba Philippines Please refer to PCN 14173 Additional information attached document.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2024-01-31
<b>7.2 Intended start of delivery</b>	2024-03-06

7.3 Qualification sample available?	Upon Request
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8. Qualification / Validation			
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8.1 Description	14173 MDG-GPM-RER2317 PCN14173 ST CLB UFQFN7x7 48L STM32G-Cx - Reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-10-25

9. Attachments (additional documentations)			
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14173 Public product.pdf 14173 MDG-GPM-RER2317 PCN14173 ST CLB UFQFN7x7 48L STM32G-Cx - Reliability plan.pdf 14173 PCN14173_Additional information.pdf			
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10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32C031C4U6	
	STM32C031C6U6	
	STM32G474CEU6	

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